

Document Revision Table

Updated December 2001

Sorted in NUMBER order, ignore all letters

Product ID	Document Name	Status	ANSI	DoD
J-STD-001	Requirements for Soldered Electrical and Electronic Assemblies	Rev. C 3/00 Rev. B 10/96 Rev. A 1/95 Orig. 4/92; Supersedes IPC-S-815	Y	Y
IPC-HDBK-001	Handbook and Guide to the Requirements for Soldered Electrical and Electronic Assemblies	Amend. 1 12/00 Orig. 3/98		Y
SMC-TR-001	An Introduction to Tape Automated Bonding Fine Pitch Technology	Orig. 1/89		
IT-WP-001	Myths of E-Commerce	Orig. 9/00		
SMC-WP-001	Soldering Capability White Paper Report	Orig. 8/91		
SMC-WP-002	An Assessment of the Use of Lead in Electronic Assembly	Orig. 8/92		
J-STD-002	Solderability Tests for Component Leads, Terminations, Lugs, Terminals and Wires	Rev. A 10/98 Orig. 4/92; Supersedes IPC-S-805	Y	
SMC-WP-003	Chip Mounting Technology	Orig. 8/93		
J-STD-003	Solderability Tests for Printed Boards	Original 4/92; Supersedes IPC-S-804	Y	
SMC-WP-004	Design for Success	Orig. 4/97		
J-STD-004	Requirements for Soldering Fluxes	Amend. 1 4/96 Orig. 1/95 Supersedes IPC-SF-818	Y	
SMC-WP-005	PWB Surface Finishes	Orig. 4/97		
IPC-HDBK-005	<i>Soldering Pastes Handbook</i>	Not yet published		
J-STD-005	Requirements for Soldering Pastes	Amend. 1 1/95 Orig. 1/95 Supersedes IPC-SF-819	Y	
J-STD-006A	Requirements for Electronic Grade Solder Alloys and Fluxed and Non-Fluxed Solid Solders for Electronic Soldering Applications	Rev. A May 01 Orig. 1/95	P	
J-STD-012	Implementation of Flip Chip and Chip Scale Technology	Orig. 1/96	Y	
J-STD-013	Implementation of Ball Grid Array and Other High Density Technology	Orig. 7/96	Y	
IPC-DRM-18	Component Identification Desk Reference Manual	Rev. E 8/00 Rev. D 7/99 Rev. C 7/98 Rev. B 2/97 Rev. A 4/96 Orig. 9/95		
J-STD-020	Moisture/Reflow Sensitivity Classification of Plastic Surface Mount Devices	Rev. A 4/99 Orig. 10/96		
J-STD-026	<i>Semiconductor Design Standard for Flip Chip Applications</i>	Orig. 8/99		
J-STD-027	<i>Mechanical Outline Standard for Flip Chip or Chip Scale Configurations</i>	Not yet published		
J-STD-028	<i>Performance Standard for Flip Chip Scale Bumps</i>	Orig. 8/99		
J-STD-029	<i>Performance and Reliability Test Methods for Flip Chip, Chip Scale, BGA, and other Surface Mount Array Package Applications</i>	Not yet published		
J-STD-030	<i>Guidelines for Selection, Application of Underfill Material for Flip Chip and Other Micropackages</i>	Not yet published		
J-STD-031	<i>Mechanical Outline Standard for Ball Grid Arrays and other High-Density Technology</i>	Not yet published		
J-STD-032	<i>Performance Standard for Ball Grid Array Bumps and Columns</i>	Not yet published		
J-STD-033	Packaging and Handling of Moisture Sensitive Non-Hermetic Solid State Surface Mount Devices	Orig. 4/99	Y	
J-STD-035	<i>Acoustic Microscopy for Non-Hermetic Encapsulated Electronic Components</i>	Orig. 4/99		
J-STD-039	Calibration Procedure for Acoustic Microscopy (AM)	Not yet published		
J-STD-040	Standards Roadmap for Optoelectronic Assembly and Packaging Technology	Not yet published		

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IPC-DRM-40	Through-Hole Solder Joint Evaluation Desk Reference Manual	Rev. D 7/00 Rev. C 9/99 Rev. B 1/99 Rev. A 8/97 Orig. 5/97		
IPC-T-50	Terms and Definitions Interconnecting and Packaging Electronic Circuits	Rev. F 6/96 Rev. E 7/92 Rev. D 11/88 Rev. C 3/85 Rev. B 6/80 Rev. A 8/76 Orig. 8/75		
IPC-DRM-53	Introduction to Electronics Assembly	Orig. 6/00		
IPC-SC-60	Post Solder Solvent Cleaning Handbook	Rev. A 8/99 Orig. 4/87		
IPC-SA-61	Post-Solder Semi-Aqueous Cleaning Handbook	Orig. 7/95		
IPC-AC-62	Post Solder Aqueous Cleaning Handbook	Rev. A 1/96 Orig. 12/86		
IPC-CH-65	Guidelines for Cleaning of Printed Boards and Assemblies	Rev. A 9/99 Orig. 12/90		
IPC-CS-70	Guidelines for Chemical Handling Safety in Printed Board Manufacturing	Orig. 8/88 Obsolete without replacement		
IPC-CM-78	Guidelines for Surface Mounting and Interconnecting Chip Carriers	Superseded by IPC-SM-780 Rev. C - 3/88 Orig. 11/83		
IPC-MP-83	IPC Policy on Metrication	Orig. 8/85 Obsolete without replacement		
IPC-PC-90	General Requirements for Implementation of Statistical Process Control	Superseded by IPC-9191 Orig. 10/90		
IPC-QS-95	General Requirements for Implementation of ISO 9000 Quality Systems	Obsolete without replacement Orig. 4/93		
IPC-L-108	Specification for Thin Metal Clad Base Materials for Multilayer Printed Boards	Rev. B 6/90 Superseded by IPC-4101 Rev. A 10/80 Orig. 3/76		
IPC-L-109	Specification for Resin Impregnated Fabric (Pregreg) for Multilayer Printed Boards	Superseded by IPC-4101 Rev. B 7/92 Rev. A 10/80 Orig. 3/76		
IPC-L-110	Preimpregnated, B-Stage Epoxy-Glass Cloth for Multilayer Printed Circuit Boards	Rev. A Superseded by IPC-L-109 and IPC-4101		
IPC-CC-110	Guidelines for Selecting Core Constructions for Multilayer Printed Wiring Board Applications	Superseded by IPC-4121 Rev. A 12/97 Orig. 1/94		
IPC-L-112	Specification for Composite Metal Clad Base materials for Printed Boards	Superseded by IPC-4101 Rev. A 6/92 Orig. 7/81		
IPC-L-115	Specification for Rigid Metal Clad Base Materials for Printed Boards	Superseded by IPC-4101 Rev. B 4/90 Rev. A 10/80 Orig. 3/77		
IPC-L-120	Inspection Procedure for Chemical Processing Suitability of Copper-Clad Epoxy-Glass Laminates	Obsolete without replacement		
IPC-L-125	Specifications for Plastic Substrates Clad or Unclad for High Speed/High Frequency Interconnections	Rev. A 7/92 Orig. 8/83		
IPC-L-130	Specifications for Thin Laminates, Metal Clad, Primarily for General-Purpose Multilayer Printed Boards	Superseded by IPC-L-108 and IPC-4101 Orig. 1/77		
IPC-DD-135	Qualification Testing for Deposited Organic Interlayer Dielectric Materials for Multichip Modules	Orig. 8/95		
IPC-EG-140	Specification for Finished Fabric Woven from "E" Glass for Printed Boards	Amend. 1 & 2 6/97 Orig. 3/88		

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IPC-SG-141	Specification for Finished Fabric Woven from "S" Glass for Printed Boards	Orig. 2/92		
IPC-A-142	Specification for Finished Fabric Woven from Aramid for Printed Boards	Orig. 6/90		
IPC-QF-143	General Specification for Finished Fabric Woven from Quartz (Pure Fused Silica) for Printed Boards	Orig. 2/92		
IPC-CF-148	Resin Coated Metal for Printed Boards	Rev. A 9/98 Orig. 6/90		
IPC-MF-150	Metal Foil for Printed Wiring Applications	Superseded by IPC-4562 Rev. F 10/91 Rev. E 5/81 Rev. D 3/76 Rev. C 8/74 Rev. B 2/71 Rev. A 9/67 Orig. 8/66		
IPC-CF-152	Composite Metallic Material Specification for Printed Wiring Boards	B 3/98 A 1/94 Orig. 6/90		
IPC-FC-203	Specification for Flat Cable, Round Conductor, Ground Plane	Obsolete 7/96 Orig. 7/85		
IPC-FC-210	Performance Specification for Flat-Conductor Undercarpet Power Cable (Type FCC)	Obsolete 7/96 Orig. 9/85		
IPC-FC-213	Performance Specification for Flat Undercarpet Telephone Cable	Obsolete 7/96 Orig. 9/84		
IPC-FC-217	General Document for Connectors, Electric, Header, Receptacle, Insulation Displacement for Use with Round Conductor Flat Cable	Obsolete 7/96 Reaffirmed 4/90 Orig. 8/82		
IPC-FC-218B/EIA-RS-429	General Specification for Connectors, Electrical Flat Cable Type	Obsolete 7/96 Reaffirmed 05/91 Reaffirmed 11/81 Orig. 7/76		
IPC-FC-219	Environment Sealed Flat Cable Connectors for use in Aerospace Applications	Obsolete 7/96 Orig. 5/84		
IPC-FC-220	Specification for Flat Cable, Flat Conductor, Unshielded	obsolete 7/96 Rev. C 7/85 Rev. B 8/75 Rev. A 1/74 Orig. 5/70		
IPC-FC-221	Specification for Flat-Copper Conductors for Flat Cables	Obsolete 7/96 Rev. A 5/84 Orig. 8/75		
IPC-FC-222	Specification of Flat Cable Round Conductor, Unshielded	Obsolete 7/96 5/91 Reaffirmed Orig. 6/80		
IPC-FC-225	Flat Cable Design Guide	Obsolete (date) 10/85 Reaffirmed Orig. 8/75		
IPC-FC-231	Flexible Base Dielectrics for Use in Flexible Printed Wiring	Amend. 10/95 Rev. C 4/92 Rev. B 2/86 Rev. A 5/83 Orig. 7/74		
IPC-FC-232	Adhesive Coated Dielectric Films for Use as Cover Sheets for Flexible Printed Wiring and Flexible Bonding Films	Amend. 10/95 Rev. C 6/94 Rev. B 2/86 Rev. A 5/83 Orig. 7/74		
IPC-FC-233	Flexible Adhesive Bonding Films	Incorporated into IPC-FC-232B		
IPC-FC-234	PSA Assembly Guidelines for Single- & Double-Sided Flexible Printed Circuits	Orig. 12/97		
IPC-FC-240	Single sided flex	Superseded by IPC-6013 Incorporated into FC-250		

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IPC-FC-241	Flexible Metal-Clad Dielectrics for Use in Fabrication of Flexible Printed Wiring	Amend. 10/95 Rev. C 4/92 Rev. B 2/86 Rev. A 5/83 Orig. 7/74		
IPC-RF-245	Performance Specification for Rigid-Flex Printed Boards	<i>Superseded by IPC-6013</i> Orig. 4/87		
IPC-D-249	Design Standard for Flexible Single-and Double-Sided Printed Boards	<i>Superseded by IPC-2223</i> Orig. 1/87		
IPC-FC-250A	Specification for Single - and Double-Sided Flexible Printed Wiring	<i>Superseded by IPC-6013</i> Rev. A 9/86 Orig. 9/86		
IPC-FA-251	Guidelines for Single and Double Sided Flex Circuits	Orig. 2/92		
IPC-D-275	Design Standard for Rigid Printed Boards and Rigid Printed Board Assemblies	Superseded by IPC-2221 and 2222 Supersedes IPC-D-319 and IPC-D-949 Amendment.1 4/96 Orig. 9/91		
IPC-RB-276	Qualification and Performance Specification for Rigid Printed Boards	Superseded by IPC-6011 and IPC-6012 Orig. 3/92 Supersedes IPC-SC-320B and IPC-ML-950C		
IPC-D-279	Design Guidelines for Reliable Surface Mount Technology Printed Board Assemblies	Orig. 7/96		
IPC-D-300	Printed Board Dimensions and Tolerances	Superseded by IPC-2615 Rev. G 1/84 Rev. F 11/74 Rev. E 10/70 Rev. D 1/70 Rev. C 10/65 Rev. B 1/64 Rev. A 7/61 Orig. 8/60		
IPC-D-310	Guidelines for Phototool Generation and Measurement Techniques	Rev. C 06/91 Rev. B 12/85 Rev. A 12/77 Orig. 9/69		
IPC-A-311	Process Control Guidelines for Phototool Generation and Use	Orig. 3/96		
IPC-D-316	Design Guide for Microwave Circuit Boards Utilizing Soft Substrates	Orig. 5/95		
IPC-D-317	Design Guidelines for Electronic Packaging Utilizing High-Speed Techniques	Rev. A 1/95 Orig. 4/90		
IPC-HF-318	Microwave End Product Board Inspection and Test	Superseded by IPC-6018 Rev. A 12/91 Orig. 6/85		
IPC-D-319	Design Standard for Rigid Single-and Double-Sided Printed Boards	Superseded by IPC-D-275, then by IPC-2221/2222 Orig. 1/87		
IPC-SD-320	Performance Specification for Rigid Single- and Double-Sided Printed Boards	Superseded by IPC-RB-276 Supersedes IPC-TC-500 Rev. B 11/86 Rev. A 3/81 Orig. 1/77		
IPC-D-322	Guidelines for Selecting Printed Wiring Board Sizes Using Standard Panel Sizes	Reaffirmed 9/91 Orig. 8/84		
IPC-MC-324	Performance Specifications for Metal Core Boards	Superseded by IPC-6011 and IPC-6012 Orig. 10/88		
IPC-D-325	Documentation Requirements for Printed Boards, Assemblies and Support Drawings	Rev. A 5/95 Orig. 1/87		
IPC-D-326	Information Requirements for Manufacturing Printed Board Assemblies	Orig. 4/91		
IPC-D-330	Design Guide Manual	Date		

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IPC-PD-335	Electronic Packaging Handbook	Orig. 12/89		
IPC-NC-349	Computer Numerical Control Formatting for Drillers and Routers	Orig. 8/85		
IPC-D-350	Printed Board Description in Digital Form; Technical Content Identical to IEC-61182-1 (PAS)	Rev. D 7/92 Rev. C 10/85 Rev. B 8/77 Rev. A 2/75 Orig. 8/72		
IPC-D-351	Printed Board Drawings in Digital Form	Orig. 8/85		
IPC-D-352	Electronic Design Data Description for Printed Boards in Digital Form	Orig. 8/85		
IPC-D-354	Library Format Description for Printed Boards in Digital Form	Orig. 2/87		
IPC-D-355	Printed Board Assembly Description in Digital Form	Orig. 1/95		
IPC-D-356	Bare Board Electrical Test Information in Digital Form	Rev. A 1/98 Orig. 3/92		
IPC-AM-361	Specification for Rigid Substrates for Additive Process Printed Boards	Superseded by IPC-4101 Orig. 1/82		
IPC-MB-380	Guidelines for Molded Interconnection Devices	Orig. 10/90		
IPC-D-390	Automated Design Guidelines	Rev. A 2/88 Orig. 7/74		
IPC-C-406	Design and Application Guidelines for Surface Mount Connectors	Orig. 1/90		
IPC-CI-408	Design and Application Guidelines for the Use of Solderless Surface Mount Connectors	Orig. 1/94		
IPC-BP-421	General Specification for Rigid Printed Board Backplanes with Press Fit Contacts	Obsolete without replacement Reaffirmed 4/90 Orig. 10/80		
IPC-D-422	Design Guide for Press Fit Rigid Printed Board Backplanes	Orig. 9/82		
IPC-DW-424	General Specification for Encapsulated Discrete Wire Interconnection Boards	Orig. 1/95		
IPC-DW-425	Design and End Product Requirements for Discrete Wiring Boards	Rev. A 5/90 Orig. 9/82		
IPC-DW-426	Specifications for Assembly of Discrete Wiring	Orig. 12/87		
IPC-TR-460	Trouble-Shooting Checklist for Wave Soldering Printed Wiring Boards	Rev. A 2/84 Orig. 1973		
IPC-TR-461	Solderability Evaluation of Thick and Thin Fused Coatings	Orig. 3/79		
IPC-TR-462	Solderability Evaluation of Printed Boards with Protective Coatings Over Long Term Storage	Orig. 10/87		
IPC-TR-464	Accelerated Aging for Solderability Evaluations	Rev. A 12/87 Orig. Pub.4/84		
IPC-TR-465-1	Round Robin Test on Steam Ager Temperature Control Stability	Orig. 1993		
IPC-TR-465-2	The Effect of Steam Aging Time and Temperature on Solderability Test Results	Orig. 1993		
IPC-TR-465-3	Evaluation of Steam Aging on Alternative Finishes, Phase IIA	Orig. 7/96		
IPC-TR-466	Wetting Balance Standard Weight Comparison Test	Orig. 4/95		
IPC-TR-467	Supporting Data and Numerical Examples for ANSI/J-STD-001 Appendix D	Orig. 10/96		
IPC-TR-468	Factors Affecting Insulation Resistance Performance of Printed Boards	Orig. 3/79		
IPC-TR-470	Thermal Characteristics of Multilayer Interconnection Boards	Orig. 1/74		
IPC-TR-474	An Overview of Discrete Wiring Techniques	Obsolete without replacement Reprint 1984 Orig. 3/79		
IPC-TR-476	How to Avoid Metallic Growth Problems on Electronic Hardware Rev. A Electrochemical Migration Electrically Induced Failures In Printed Assemblies	Rev. A 6/84 (new title) Orig. 9/77		
IPC-TR-480	Results of Multilayer Test Program Round Robin IV Phase I	Obsolete without replacement Orig. 9/75		
IPC-TR-481	Results of Multilayer Test Program Round Robin V	Orig. 4/81		
IPC-TR-482	New Developments in Thin Copper Foils	Orig. 7/93		

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IPC-TR-483	Dimensional Stability Testing of Thin Laminates - Report on Phase I International Round Robin Test Program	Rev. A 3/91 Addendums 10/87 Orig. 4/84		
IPC-TR-484	Results of IPC Cooper Foil Ductility Round Robin Study	Orig. 4/86		
IPC-TR-485	Results of Cooper Foil Rupture Strength Test Round Robin Study	Orig. 3/85		
IPC-TR-486	<i>Report on Round Robin Study to Correlate Interconnect Stress Test (IST) with Thermal Stress/Microsectioning Evaluations for Detecting the Presence of Inner-layer Separations</i>	Orig. 07/01		
IPC-TR-549	Measles in Printed Wiring Boards	Orig. 11/73		
IPC-TR-551	Quality Assessment of Printed Boards Used for Mounting and Interconnecting Electronic Components	Orig. 7/93		
IPC-DR-570	General Specification for 1/8 Inch Diameter Shank Carbide Drills for Printed Boards	Rev. A 4/84 Orig. 1/79		
IPC-DR-572	Drilling Guidelines for Printed Boards	Orig. 4/88		
IPC-TR-576	Additive Process Evaluation	Obsolete without replacement Orig. 9/77		
IPC-TR-578	Leading Edge Manufacturing Technology Report - Resulting of a Round Robin Study on Minimum Conductor Width and Plated-Through Holes in Rigid, Bare Copper, Double-Sided Printed Wiring Boards	Orig. 9/84		
IPC-TR-579	Round Robin Reliability Evaluation of Small Diameter Plated Through Holes in Printed Wiring Boards	Orig. 9/88		
IPC-TR-580	Cleaning and Cleanliness Test Program Phase 1 Test Results	Orig. 10/89		
IPC-TR-581	IPC Phase 3 Controlled Atmosphere Soldering Study	Orig. 8/94		
IPC-TR-582	IPC Phase 3 No-Clean Flux Study	Orig. 11/94		
IPC-A-600	Acceptability of Printed Boards	Rev. F 11/99 Rev. E 8/95 Rev. D '89 Rev. C '78 Rev. B '74 Rev. A '70 Orig. '64		
IPC-SS-605	Printed Board Quality Evaluation Slide Set	Obsolete without replacement		
IPC-QE-605	Printed Board Quality Evaluation Handbook	Rev. A 2/99		
IPC-A-610	Acceptability of Electronic Assemblies	Rev. C 1/00 Rev. B 12/94 Rev. A 3/90 Orig. 8/83		
IPC-QE-615	Assembly Quality Evaluation Handbook	Orig. 3/93		
IPC/WHMA-A-620	<i>Acceptability of Electronic Wire Harnesses and Cables</i>	Not yet published		
IPC-AI-640	User's Guidelines for Automated Inspection of Unpopulated Thick Film Hybrid Substrates	Obsolete without replacement Orig. 1/87		
IPC-AI-641	User's Guidelines for Automated Solder Joint Inspection	Obsolete without replacement Orig. 1/87		
IPC-AI-642	User's Guidelines for Automated Inspection of Artwork, Interlayers, and Unpopulated PWB's	Obsolete without replacement Orig. 10/88		
IPC-OI-645	Standard for Visual Optical Inspection Aids	Orig. 10/93		
IPC-TM-650	Test Methods Manual	Updated per test method		
IPC-ET-652	Guidelines and Requirements for Electrical Testing of Unpopulated Printed Boards	Orig. 10/90 Superseded by IPC-9252		
IPC-QL-653	Qualification of Facilities that Inspect/Test Printed Boards, Components, and Material	Rev. A 11/97 Orig. 8/88		
IPC-MI-660	Incoming Inspection of Raw Materials Manual	Orig. 2/84		
IPC-R-700	Suggested Guidelines for Modification, Rework and Repair of Printed Boards and Assemblies	Superseded by IPC-7711 and 7721 C 1/88 B 9/77 A 12/71 Orig. 9/67		
IPC-TA-720	Technology Assessment Handbook on Laminates			

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IPC-TA-721	Technology Assessment Handbook on Multilayer Boards			
IPC-TA-722	Technology Assessment of Soldering			
IPC-TA-723	Technology Assessment Handbook on Surface Mounting			
IPC-TA-724	Technology Assessment Series on Cleanrooms	Orig. 4/98		
IPC-PE-740	Troubleshooting Guide for Printed Board Manufacture and Assembly	Rev. A 12/97 Orig. 1/85		
IPC-CM-770	Printed Board Component Mounting	Rev. D 1/96 Rev. C 1/87 Rev. B 10/80 Rev. A 3/76 Orig. 9/68		
IPC-SM-780	Component Packaging and Interconnecting with Emphasis on Surface Mounting	Orig. 3/88		
IPC-SM-782	Surface Mount Design and Land Pattern Standard	Amend. 2 04/99 Amend. 1 10/96 Rev. A 8/93 Orig. 3/87		
IPC-EM-782	Surface Mount Design and Land Pattern Spreadsheet	Addendum 12/95 Orig. 9/94		
IPC-SM-784	Guidelines for Chip-on-Board Technology Implementation	Orig. 11/90		
IPC-SM-785	Guidelines for Accelerated Reliability Test of Surface Mount Solder Attachments	Orig. 11/92		
IPC-SM-786	Procedures for Characterizing and Handling of Moisture/ Reflow Sensitive ICs	Superseded by J-STD-020 and J-STD-033 Rev. A 1/95 Orig. 12/90		
IPC-MC-790	Guidelines for Multichip Module Technology Utilization	Orig. 8/92		
IPC-S-804	Solderability Test Methods for Printed Wiring Boards	Superseded by J-STD-003 Rev. A 1/87 Orig. 1/82		
IPC-S-805	Solderability Tests for Component Leads and Terminations	Superseded by J-STD-002 Orig. 1/85		
IPC-MS-810	Guidelines for High Volume Microsection	Orig. 10/93		
IPC-S-815	General Requirements for Soldering Electronic Interconnections	Superseded by J-STD-001 Rev. B 12/87 Rev. A 6/81 Orig. 11/77		
IPC-S-816	SMT Process Guideline and Checklist	Orig. 7/93		
IPC-SM-817	General Requirements for Dielectric Surface Mounting Adhesives	Orig. 11/89		
IPC-SF-818	General Requirement for Electronic Soldering Fluxes	Superseded by J-STD-004 Rev. 12/91 Orig. 2/88		
IPC-SP-819	General Requirements and Test Methods for Electronic Grade Solder Paste	Orig. 10/88 Superseded by J-STD-005		
IPC-AJ-820	Assembly and Joining Manual	Orig. 8/96		
IPC-CA-821	General Requirements for Thermally Conductive Adhesives	Orig. 1/95		
IPC-CC-830	Qualification and Performance of Electronic Insulating Compound for Printed Board Assemblies	Amend. 1 7/99 Rev. A 10/98 Orig. 1/84		
IPC-HDBK-830	<i>Conformal Coating Handbook</i>	Not yet published		
IPC-SM-839	Pre and Post Solder Mask Application Cleaning Guidelines	Orig. 4/90		
IPC-SM-840	Qualification and Performance of Permanent Polymer Coating (Solder Mask) for Printed Boards	Amend. 1 6/00 Rev. C 1/96 Rev. B 5/88 Rev. A 7/83 Orig. 11/77		
IPC-H-855	Hybrid Microcircuit Design Guide	Obsolete without replacement Orig. 10/82		
IPC-D-859	Design Standard for Thick Film Multilayer Hybrid Circuits	Orig. 12/89		

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IPC-HM-860	Specification for Multilayer Hybrid Circuits	Orig. 1/87		
IPC-TF-870	Qualification and Performance of Polymer Thick Film Printed Boards	Orig. 11/89		
IPC-ML-910	Design and End Production Specification for Rigid Multilayer Printed Boards	Superseded by IPC-D-949, IPC-D-275, and subsequently IPC-2221 for Design and IPC-ML-950, IPC-RB-276, and subsequently IIPC-6011 for End Product Specification Rev. A 08/76 Orig. 06/68		
IPC-D-949	Design Standard for Rigid Multilayer Printed Boards	Superseded by IPC-D-275 and subsequently by IPC-2221/2222 Orig. 1/87		
IPC-ML-950	Performance Specification for Rigid Multilayer Printed Boards	Superseded by IPC-RB-276 and subsequently IPC-6011/6012 Rev. C 11/8 Rev. B 12/77 Rev. A 9/70 Orig. 1/66		
IPC-ML-960	Qualification and Performance Specification for Mass Laminated Panels for Multilayer Printed Boards	Orig. 7/94		
IPC-ML-975	End Product Documentation Specification for Multilayer Printed Wiring Boards	Superseded by IPC-D-325 Orig. 9/69		
IPC-ML-990	Performance Specification for Flexible Multilayer Wiring	Superseded by IPC-6011 Orig. 9/72		
IPC-1043	Cleaning & Cleanliness Test Program Phase 3 Water Soluble Fluxes Part 1	Orig. 8/92		
IPC-1044	Cleaning & Cleanliness Test Program Phase 3 Water Soluble Fluxes Part 2	Orig. 10/92		
IPC-TP-1090	<i>The Layman's Guide to Qualifying New Fluxes for MIL-STD-2000A or MT-0002</i>	Orig. 7/96		
IPC-TP-1103	<i>Manufacturing Concerns When Soldering with Gold Plated Component Leads or Circuit Board Pads</i>	Obsolete without replacement		
IPC-TP-1114	<i>The Layman's Guide to Qualifying a Process to J-STD-001B</i>	Orig. 1/98		
IPC-TP-1115	<i>Selection and Implementation Strategy for A Low-Residue No-Clean Process</i>	Orig. 12/98		
IPC-1131	<i>IT Guidelines for PWB Manufacturers</i>	Orig. 04/00		
IPC-1331	<i>Voluntary Safety Standard for Electrically Heated Process Equipment</i>	Orig. 3/00		
IPC-1710	OEM Standard for Printed Board Manufacturers' Qualification Profile (MQP)	12/97 updated Orig. 2/94		
IPC-1720	Assembly Qualification Profile (AQP)	Orig. 7/96		
IPC-1730	Laminator Qualification Profile (LQP)	Rev. A 6/00 Orig. 1/98		
IPC-1731	<i>Strategic Raw Materials Supplier Qualification Profile</i>	Orig. Pub. 6/00		
IPC-1902	IPC/IEC Grid Systems for Printed Circuits	Orig. Pub. 12/98		
IPC-2141	Controlled Impedance Circuit Boards and High Speed Logic Design	Orig. 4/96		
IPC-2221	Generic Standard on Printed Board Design	Supersedes IPC-D-275 Amend. 1 01/00 Orig. 2/98		
IPC-2222	Sectional Design Standard for Rigid Organic Printed Boards	Supersedes IPC-D-275 Orig. 2/98		
IPC-2223	Sectional Design Standard for Flexible Printed Boards	Supersedes IPC-D-249 Orig. 11/98		
IPC-2224	<i>Sectional Standard for Design of PWBs for PC Cards</i>	Orig. 01/98		
IPC-2225	<i>Sectional Design Standard for Organic Multichip Modules (MCM-L) and MCM-L Assemblies</i>	Orig. 05/98		
IPC-2226	<i>Design Standard for High-Density Array or Peripheral Ledged Component Mounting Structures</i>	Not yet published		

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IPC-2251	<i>Design Guidelines for Electronic Packaging Utilizing High Speed Techniques</i>	Not yet published		
IPC-2252	<i>Design and Manufacturing Guide for RF/Microwave Circuit Boards</i>	Orig. Pub.		
IPC/JPCA-2315	<i>Design Guide for High Density Interconnects (HDI) and Microvia</i>	Orig. 06/00		
IPC-2401		Not yet published		
IPC-2431		Not yet published		
IPC-2511	<i>Generic Requirements for Implementation of Product Manufacturing Description Data and Transfer Methodology</i>	Rev A 01/00		
IPC-2512A	<i>Sectional Requirements for Implementation of Administrative Methods for Manufacturing Data Description</i>	Rev A 11/00		
IPC-2513		Rev A 11/00		
IPC-2514	<i>Sectional Requirements for Implementation of Printed Board Manufacturing Data Description</i>	Rev A 11/00		
IPC-2515	<i>Sectional Requirements for Implementation of Bare Board Product Electrical Testing Data Description</i>	Rev A 11/00		
IPC-2516	<i>Sectional Requirements for Implementation of Assembled Board Product Manufacturing Data Description</i>	Rev A 11/00		
IPC-2517	<i>Sectional Requirements for Implementation of Assembly In-Circuit Testing Data Description – 2-11gChair, Bob Neal, Agilent Technologies</i>	Rev A 11/00		
IPC-2518	<i>Sectional Requirements for Implementation of Part List Product Data Description - Chair, Harry Parkinson, Parkinson Consulting</i>	Rev A 11/00		
IPC-2524	<i>PWB Fabrication Data Quality Rating System</i>	Orig. 02/99		
IPC-2531	<i>Standard Recipe File Format Specification</i>			
IPC-2541	<i>Generic Requirements for Electronic Manufacturing Shop Floor Equipment Communication</i>	Not yet published		
IPC-2546	<i>Sectional Requirements for Shop Floor Electronic Assembly Equipment Communication</i>	Not yet published		
IPC-2547	<i>Sectional Requirements for Shop Floor Electronic Inspection and Test Equipment Communication</i>	Not yet published		
IPC-2571	<i>Generic Requirements for Electronic Manufacturing Supply Chain Communication-Product Data Exchange (PDX)</i>	Not yet published		
IPC-2576	<i>Sectional Requirements for Electronics Manufacturing Supply Chain Communication of As-Built Product Data - Product Exchange (PDX)</i>	Not yet published		
IPC-2577	<i>Sectional Requirements for Supply Chain Communications of Manufacturing Quality Assessment -- Product Data Exchange (PDX)</i>	Not yet published		
IPC-2578	<i>Sectional Requirements for Supply Chain Communication of Bill of material and Product Design Configuration Data-Product Data Exchange (PDX)</i>	Not yet published		
IPC-2615	<i>Printed Board Dimensions and Tolerances</i>	<i>Supersedes IPC-D-300</i> Orig. 06/00		
IPC-3406	<i>Guidelines for Electrically Conductive Surface Mount Adhesives</i>	Orig. 7/96		
IPC-3408	<i>General Requirements for Anistropically Conductive Adhesive Films</i>	Orig. 11/96		
IPC-4101	<i>Specification for Base Materials for Rigid and Multilayer Boards</i>	<i>Supersedes IPC-L-108, IPC-L-109, IPC-L-112, IPC-L-115</i> Orig. 12/97		
IPC-4103	<i>Specification for Plastic Substrates, Clad or Unclad, for High Speed/High Frequency Interconnection</i>	Not yet published		
IPC-4104 -	<i>Specification for High Density Interconnect (HDI) and Microvia Materials</i>	Orig. 5/99		
IPC-4110	<i>Specification and Characterization Methods for Nonwoven Cellulose Based Paper for Printed Boards</i>	Orig. 8/98		
IPC-4121	<i>Guidelines for Selecting Core Constructions for Multilayer Printed Wiring Board Applications</i>	Supersedes IPC-CC-110A Orig. 1/00		
IPC-4130	<i>Specification and Characterization Methods for Nonwoven "E" Glass Mat</i>	Orig. 9/98		

Product ID	Document Name	Status	ANSI	DoD
IPC-4202	<i>Flexible Base Dielectrics for Use in Flexible Printed Wiring</i>	Not yet published, will supersede IPC-FC-231C		
IPC-4203	<i>Adhesive Coated Dielectric Films for Use as Cover Sheets</i>	IPC-FC-232C Not yet published Supersedes		
IPC-4204	<i>Flexible Metal-Clad Dielectrics for Use in Fabrication of</i>	Not yet published, will supersede IPC-FC-241C		
IPC-4411	<i>Specification and Characterization Methods for Nonwoven Para-Aramid Reinforcement</i>	Orig. 4/99		
IPC-4412	<i>Specification for Finished Fabric Woven form "E" Glass for Printed Boards</i>	Not yet published, will supersede IPC-EG-140A		
IPC-4552	<i>Electroless Nickel/Immersion Gold (ENIG) Plating for Electronic Interconnections</i>	Not yet published		
IPC-4562	<i>Metal Foil for Printed Wiring Applications</i>	Supersedes IPC-MF-150G Orig. 5/00		
IPC-4563	<i>Resin-Coated Metal Foil for Printed Boards</i>	Not yet published, will supersede IPC-CF-148A		
IPC-4902	<i>Specification for Materials for Embedded Passive Devices for Printed Boards</i>	Not yet published		
IPC-TC-500	Through-hole standard			
IPC-TC-550				
IPC-6011	Generic Performance Specification for Printed Boards	Orig. 7/96		
IPC-6012	Qualification and Performance Specification for Rigid Printed Boards	Amend. 1 7/00 Rev. A 10/99 Orig. 7/96		
IPC-6013	Qualification and Performance Specification for Flexible Printed Boards	Supersedes IPC-RF-245 and IPC-FC-250 Amend. 1 04/00 Orig. 11/98		
IPC-6015	Qualification and Performance Specification for Organic Multichip Module (MCM-L) Mounting and Interconnecting Structures	Orig. 2/98		
IPC-6016	Qualification and Performance Specification for High Density Interconnect (HDI) Layers or Boards	Orig. 05/99		
IPC-6018	Microwave End Product Board Inspection and Test	Orig. 1/98		
IPC/JPCA-6202	Performance Guide Manual for Single- and Double-Sided Flexible Printed Wiring Boards	Orig. 2/99		
PAS-62084	<i>Implementation of Flip Chip and Chip Scale Technology</i>			
PAS-62119	<i>Generic Requirements for Implementation of Product Manufacturing Description Data & TRFR methodology</i>			
PAS-62123	<i>Performance Guide Manual for Single & Double Sided flexible pwb</i>			
IPC/JPCA-6801	<i>Terms & Definitions, Test Methods, and Design Examples for Build-Up/High Density Interconnection</i>	Orig. 1/00		
IPC-7070 Series	<i>General Requirements for Component Mounting</i>	Not yet published		
IPC-7071	<i>General Requirements for Component Mounting</i>	Not yet published		
IPC-7072	<i>Sectional Requirements for Through-Hole Component Mounting</i>	Not yet published		
IPC-7073	<i>Sectional Requirements for Standard Surface Mount Technology Component Mounting</i>	Not yet published		
IPC-7074	<i>Sectional Requirements for Fine Pitch and High Pin Count Component Mounting</i>	Not yet published		
IPC-7075	<i>Sectional Requirements for High Pin Count Area Array Component Mounting</i>	Not yet published		
IPC-7076	<i>Sectional Requirements for Chip Scale and Chip Size Component Mounting</i>	Not yet published		
IPC-7077	<i>Sectional Requirements for Wire Bonding Bare Chip Component Mounting</i>	Not yet published		
IPC-7078	<i>Sectional Requirements for Flip Chip Component Mounting (Direct Chip Attach)</i>	Not yet published		
IPC-7095	Design and Assembly Process Implementation for BGAs	Orig. 8/00		
IPC-7525	<i>Guidelines for Stencil Design</i>	Orig. 5/00		

Product ID	Document Name	Status	ANSI	DoD
IPC-7526	<i>Stencil and Misprinted Board Cleaning Handbook</i>	Not yet published		
IPC-7530	<i>Guidelines for Temperature Profiling for Mass Soldering (Wave and Reflow) Processes</i>	Orig. 5/01		
IPC-7711	Rework of Electronic Assemblies	Orig. 4/98 <i>Supersedes IPC-R-700C</i>		
IPC-7721	Repair and Modification of Printed Boards and Electronic Assemblies	Orig. 4/98 <i>Supersedes IPC-R-700C</i> Ch1 & 2 available		
IPC-7912	<i>Calculation of DPMO and Manufacturing Indices for Printed Wiring Assemblies</i>	Orig. 7/00		
IPC-S-801		Superseded by IPC-804 and J-STD-003		
IPC-S-803		Superseded by IPC-804 and J-STD-003		
IPC-9191	General Guideline for implementation of Statistical Process Control (SPC)	Supersedes IPC-PC-90 Orig. 11/99		
IPC-9192	<i>Implementation of Statistical Process Control (SPC) Applied to Printed Board Interconnection Base Materials</i>	Not yet published		
IPC-9193	<i>SPC Implementation Requirements Applied to Printed Board and Interconnection Structure Manufacture</i>	Not yet published		
IPC-9194	<i>Implementation of Statistical Process Control (SPC) Applied to Printed Board Assembly Manufacture</i>	Not yet published		
IPC-9199	<i>SPC Quality Rating</i>	Not yet published		
IPC-9201	Surface Insulation Resistance Handbook	Orig. 7/96		
PAS-62085	<i>Implementation of Ball Grid Array and Other High Density Technology</i>			
IPC-9251	<i>Test Vehicles for Evaluating Fine Line Capability</i>	Orig. 7/00		
IPC-9252	<i>Guidelines and Requirements for Electrical Testing of Unpopulated Printed Boards</i>	Supersedes IPC-ET-652A Orig. 02/01		
IPC-9261	<i>In-Process DPMO and Estimated Yield for PWAs</i>	Not yet published		
IPC-9501	PWB Assembly Process Simulation for Evaluation of Electronic Components	Orig. 7/95		
IPC-9502	<i>PWB Assembly Soldering Process Guidelines for Non-IC Electronic Components</i>	Orig. 4/99		
IPC-9503	<i>Moisture Sensitivity Classification for Non-IC Components</i>	Orig. 4/99		
IPC-9504	Assembly Process Simulation for Evaluation of Non-IC Components	Orig. 6/98		
IPC-9701	<i>Qualification and Performance Test Methods for Surface Mount Solder Attachments</i>	Not yet published		
IPC-9850	<i>Surface Mount Equipment Performance Characterization</i>	Not yet published		
IPC-DRM-SMT	Surface Mount Solder Joint Evaluation Desk Reference Manual	Rev. B 4/00 Rev. A 3/99 Orig. 7/98		
IPC-EMSI-TC	EMSI Terms & Conditions			
Roadmap	National Technology Roadmap for Electronic Interconnections	Updated 2001 Updated 9/97 Orig. 6/95		
SMEMA 1.2	<i>Mechanical Equipment Interface Standard</i>	Update IPC-SMEMA-9851 not yet published		
SMEMA 3.1	<i>Fiducial Mark Standard</i>			
SMEMA 4	<i>Reflow Terms and Definitions</i>			
SMEMA 5	<i>Screen Printing Terms and Definitions</i>			
SMEMA 6	<i>Electronics Cleaning Terms and Definitions</i>			
SMEMA 7	<i>Fluid Dispensing Terms and Definitions</i>			